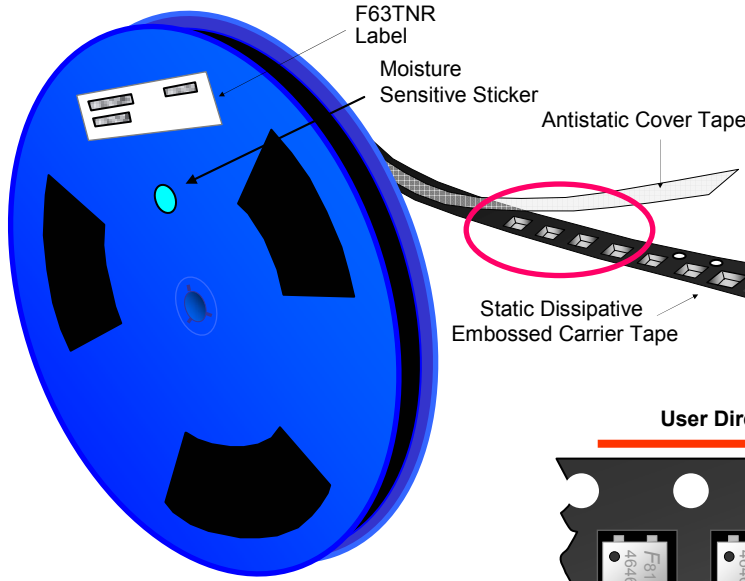


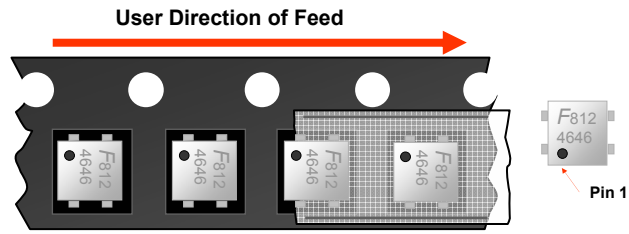
3.5 x 4.0 FLF MOSFET BGA Packaging Configuration: Figure 1.0



Packaging Description:
 3.5 x 4.0 FLF MOSFET BGA parts are shipped in tape. The carrier tape is made from a dissipative (carbon filled) polystyrene or polycarbonate resin. The cover tape is a multilayer film. It comes either in HAA (Heat Activated Adhesive) or PSA (Pressure Sensitive Adhesive) composition which is both static dissipative in nature. These reeled parts in standard option are shipped with 3,000 units per 13" or 330mm diameter reel. The reels are dark blue or black in color and is made of polystyrene plastic (anti-static coated).
 These full reels are individually barcode labeled, vacuum packed and placed inside a pizza box (illustrated in figure 1.0) made of recyclable corrugated brown paper. One box contains one reel maximum. Multiple of this box are placed inside a barcode labeled shipping box which comes in different sizes depending on the number of parts shipped.

3.5 x 4.0 FLF MOSFET BGA Packaging Information

Packaging Option	Standard (no flow code)
Packaging type	TNR
Qty per Reel/Tube/Bag	3,000
Reel Size	13" Dia
Box Dimension (mm)	338x334x43
Max qty per Box	3,000
Weight per unit (gm)	0.0490
Weight per Reel (kg)	0.5900
Note/Comments	



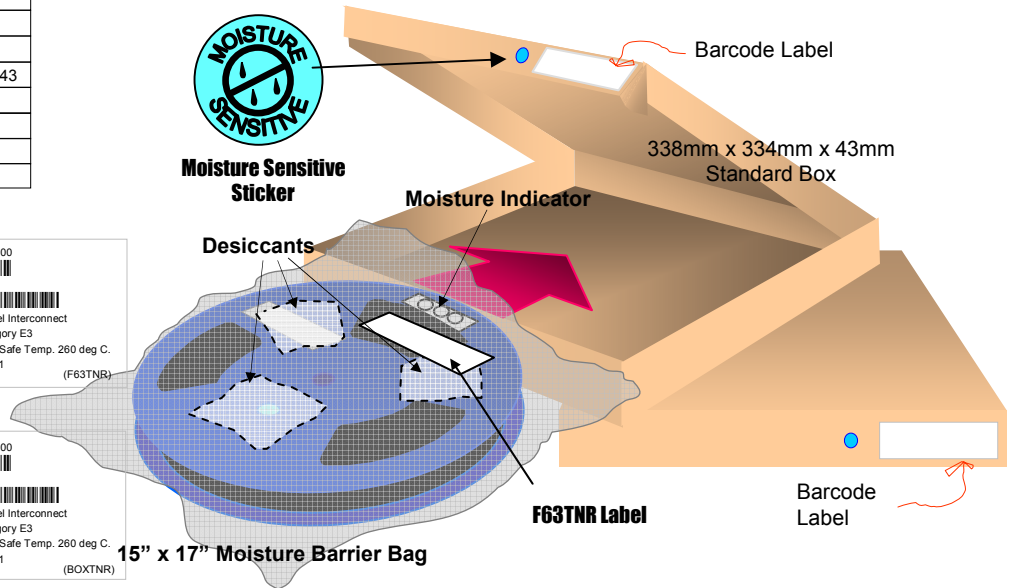
Mosfet BGA Unit Orientation

F63TNR Label sample

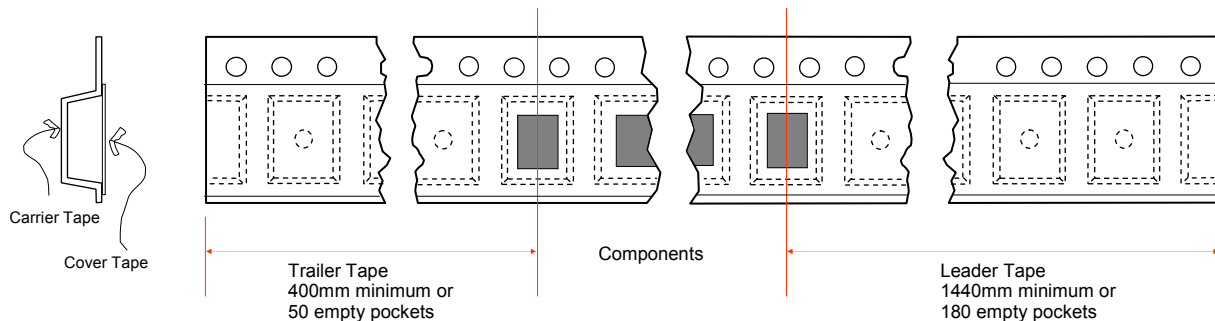
LOT: D010125632 QTY: 3000
 PART ID: FDZ4646 SPEC:
 DIC1: D0812AB QTY1: 3000 2nd Level Interconnect
 1. Category E3
 DIC2: QTY2: RoHS COMPLIANT 2. Max. Safe Temp. 260 deg C.
 3. MSL 1 (F63TNR)
 FAIRCHILD SEMICONDUCTOR

BOXTNR Label sample

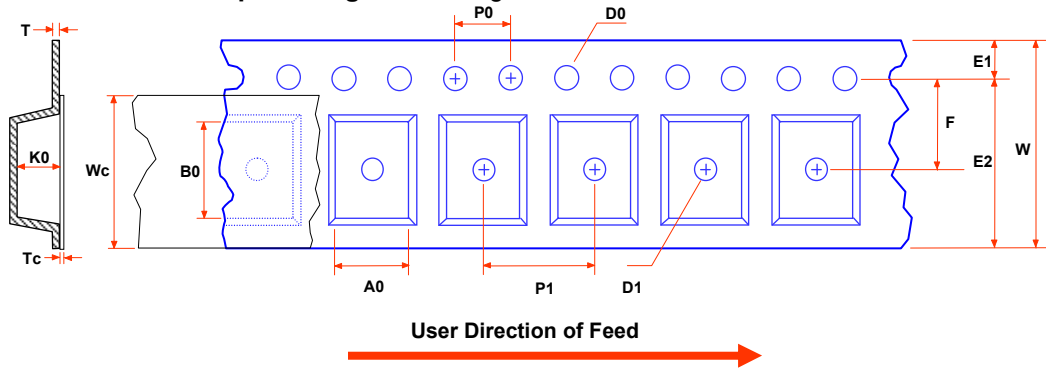
LOT: D010125632 QTY: 3000
 PART ID: FDZ4646 SPEC:
 DIC1: D0812AB QTY1: 3000 2nd Level Interconnect
 1. Category E3
 DIC2: QTY2: RoHS COMPLIANT 2. Max. Safe Temp. 260 deg C.
 3. MSL 1 (BOXTNR)
 FAIRCHILD SEMICONDUCTOR



3.5 x 4.0 FLF MOSFET BGA Tape Leader and Trailer Configuration: Figure 2.0

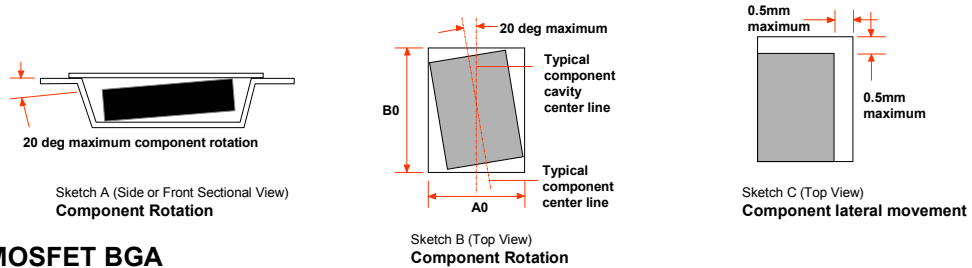


3.5 x 4.0 FLF MOSFET BGA Embossed Carrier Tape Configuration: Figure 3.0

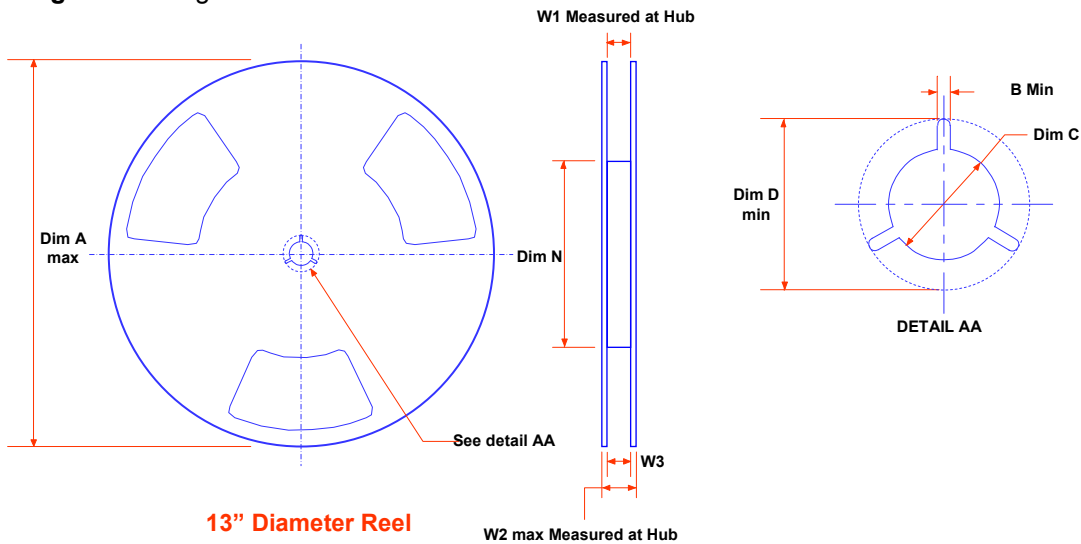


Dimensions are in millimeter														
Pkg type	Ao	Bo	W	Do	D1	E1	F	P1	P2	Po	Ko	T	Wc	Tc
3.5 x 4.0 FLF BGA (12mm)	3.70 +/- 0.05	4.35 +/- 0.05	12.0 +/- 0.10	1.55 +/- 0.05	1.55 +/- 0.05	1.75 +/- 0.10	5.50 +/- 0.05	8.00 +/- 0.10	2.00 +/- 0.05	4.00+ /- 0.10	1.00 +0.10 / 0.05	0.23 +/- 0.05	9.20 +/- 0.30	0.06 +/- 0.02

Notes: A0, B0, and K0 dimensions are determined with respect to the EIA/Jedec RS-481 rotational and lateral movement requirements (see sketches A, B, and C).



3.5 x 4.0 FLF MOSFET BGA Configuration: Figure 4.0



Dimensions are in inches and millimeters									
Tape Size	Reel Option	Dim A	Dim B	Dim C	Dim D	Dim N	Dim W1	Dim W2	Dim W3 (LSL-USL)
12mm	13" Dia	13.00 330	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	7.00 178	0.488 +0.078/-0.000 12.4 +2/0	0.724 18.4	0.469 - 0.606 11.9 - 15.4